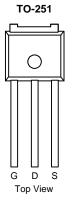
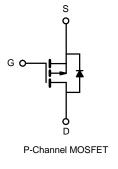


AP4419GJ-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.018 at V _{GS} = - 10 V	- 40	13 nC		
- 30	0.022 at V _{GS} = - 4.5 V	- 35	13110		





FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFET
- 100 % Rg Tested

APPLICATIONS

- Load Switch
- Battery Switch

ABSOLUTE MAXIMUM RATINGS T_A	= 25 °C, unless othe	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 30	V
Gate-Source Voltage		V _{GS}	± 20	v
	T _C = 25 °C		- 40	
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C		- 35	
Continuous Drain Current (1) = 130°C)	T _A = 25 °C	۱ _D	- 30.0 ^{a, b}	
	T _A = 70 °C		- 28 ^{a, b}	A
Pulsed Drain Current		I _{DM}	- 150	
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	- 3.5	
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	- 2.1 ^{a, b}	
	T _C = 25 °C		40	
Maximum Dawar Dissinction	T _C = 70 °C	P	32	w
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	vv
	T _A = 70 °C	1	1.6 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	0/10	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 95 °C/W.

d. Based on $T_C = 25$ °C.

HALOGEN

Available

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SPECIFICATIONS T _J = 25 °C, unless otherwise noted Parameter Symbol Test Conditions Min. Typ. Max. Uni						
Static	Symbol	Test conditions	IVIII.	Тур.	IVIdX.	Unit
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J			- 31		v
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1.0	4.5	- 2.5	V
Gate-Source Leakage		$V_{DS} = 0 V, V_{GS} = \pm 20 V$	- 1.0		+ 2.5 ± 100	nA
Gale-Source Leakage	I _{GSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = -20 \text{ V}$			± 100 - 1	ΠA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 1	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 V, V_{GS} = -10 V$	- 20			А
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -7.0 \text{ A}$ $V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5.6 \text{ A}$		0.018		Ω
Forward Transpoorducton and	0,	$V_{DS} = -15 \text{ V}, \text{ I}_{D} = -7.0 \text{ A}$		18		S
Forward Transconductance ^a	9 _{fs}	VDS = - 13 V, 10 = - 7.0 A		10		3
Dynamic ^b	<u> </u>			4455		
Input Capacitance	C _{iss}	$V_{1} = 15 V_{1} V_{2} = 0 V_{1} f_{1} = 1 M_{1} J_{2}$		1455		
Output Capacitance	C _{oss}	$V_{DS} = -15 V$, $V_{GS} = 0 V$, f = 1 MHz		180		pF
Reverse Transfer Capacitance	C _{rss}			145		
Total Gate Charge	Qg	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 7.0 A		25 13	38 20	
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 7.0 A		3.5		nC
Gate-Drain Charge	Q _{gd}			5.5		
Gate Resistance	R _q	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t _{d(on)}			10	20	
Rise Time	t _r	V_{DD} = - 15 V, R _L = 2.7 Ω		13	20	-
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 5.6 A, V_{GEN} = - 10 V, R_a = 1 Ω		23	35	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			38	57	ns
Rise Time	t _r	V_{DD} = - 15 V, R _L = 2.7 Ω		89	134	
Turn-Off DelayTime	t _{d(off)}			22	33	1
Fall Time	t _f			11	17	
Drain-Source Body Diode Characteris						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 6.5	
Pulse Diode Forward Current	I _{SM}	0			- 30	A
Body Diode Voltage	V _{SD}	I _S = - 5.6 A, V _{GS} = 0 V		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			22	33	ns
Body Diode Reverse Recovery Charge				17	26	nC
t_a $I_F = -5.6 \text{ A}, dI/dt = 100 \text{ J}$ Reverse Recovery Rise Time t_b		I _F = - 5.6 A, dI/dt = 100 A/μs, T _J = 25 °C		13	-	
			9			ns

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



T_C = - 55 °C

T_C = 25 °C

2.0

18

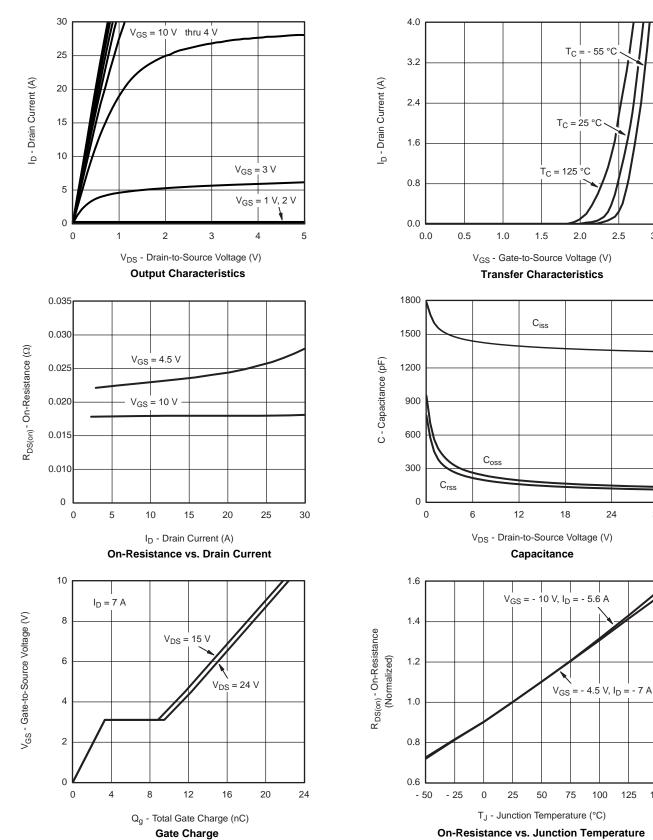
24

5.6 A

30

2.5

3.0



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

125

75

100

150



I_D = 7 A

T_J = 125 °C

T_J = 25 °C

16

10

100

20

4

0.01

S

10 s DC

100

BVDSS

Limited

10

V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified Safe Operating Area

0.1

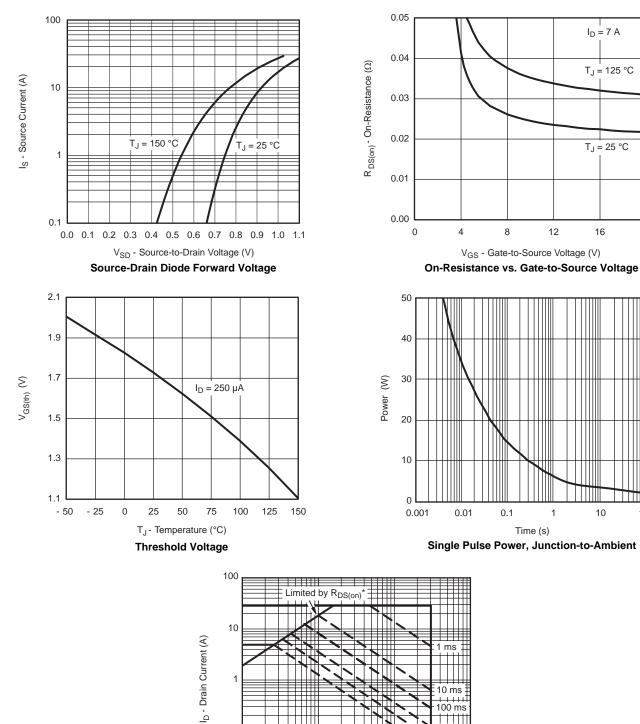
1

Time (s)

8

12

 V_{GS} - Gate-to-Source Voltage (V)



0.1

0.01 0.1 T_A = 25 °C Single Pulse

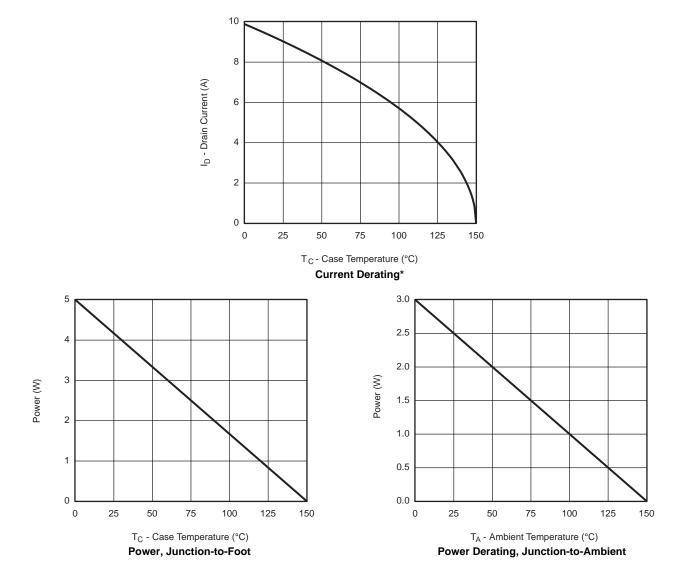
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

服务热线:400-655-8788



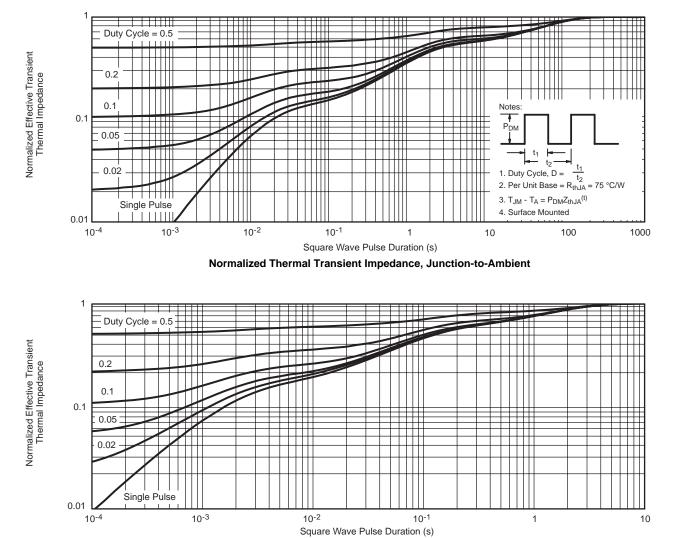
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



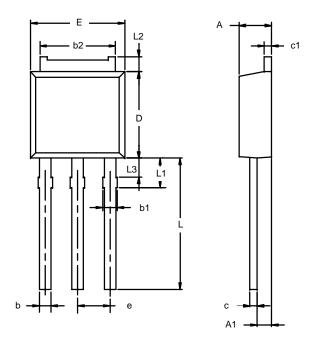
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-0 DWG: 53	3946—Rev. E 46	, 09-Jul-01			



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